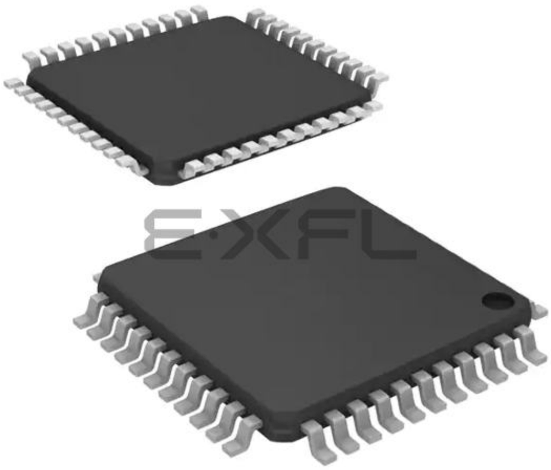

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx150f128dt-50i-pt

TABLE 13: PIN NAMES FOR 44-PIN GENERAL PURPOSE DEVICES

44-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX110F016D
PIC32MX120F032D
PIC32MX130F064D
PIC32MX130F256D
PIC32MX150F128D
PIC32MX170F256D

44 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/CTED11/PMD2/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/PMD1/RB11	31	OSC2/CLKO/RPA3/RA3
10	AN12/PMD0/RB12	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4(4)/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4(4)/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14	36	RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0	41	PGED3/RPB5/PMD7/RB5
20	VREF-/CVREF-/AN1/RPA1/CTED2/RA1	42	PGEC3/RPB6/PMD6/RB6
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.
2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.
3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
4: This pin function is not available on PIC32MX110F016D and PIC32MX120F032D devices.
5: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
SDA1	15	18	19	1	I/O	ST	Synchronous serial data input/output for I2C1
SCL2	4	7	2	24	I/O	ST	Synchronous serial clock input/output for I2C2
SDA2	3	6	1	23	I/O	ST	Synchronous serial data input/output for I2C2
TMS	19(2) 11(3)	22(2) 14(3)	25(2) 15(3)	12	I	ST	JTAG Test mode select pin
TCK	14	17	18	13	I	ST	JTAG test clock input pin
TDI	13	16	17	35	O	—	JTAG test data input pin
TDO	15	18	19	32	O	—	JTAG test data output pin
RTCC	4	7	2	24	O	ST	Real-Time Clock alarm output
CVREF-	28	3	34	20	I	Analog	Comparator Voltage Reference (low)
CVREF+	27	2	33	19	I	Analog	Comparator Voltage Reference (high)
CVREFOUT	22	25	28	14	O	Analog	Comparator Voltage Reference output
C1INA	4	7	2	24	I	Analog	Comparator Inputs
C1INB	3	6	1	23	I	Analog	
C1INC	2	5	36	22	I	Analog	
C1IND	1	4	35	21	I	Analog	
C2INA	2	5	36	22	I	Analog	
C2INB	1	4	35	21	I	Analog	
C2INC	4	7	2	24	I	Analog	
C2IND	3	6	1	23	I	Analog	
C3INA	23	26	29	15	I	Analog	
C3INB	22	25	28	14	I	Analog	
C3INC	27	2	33	19	I	Analog	
C3IND	1	4	35	21	I	Analog	
C1OUT	PPS	PPS	PPS	PPS	O	—	Comparator Outputs
C2OUT	PPS	PPS	PPS	PPS	O	—	
C3OUT	PPS	PPS	PPS	PPS	O	—	

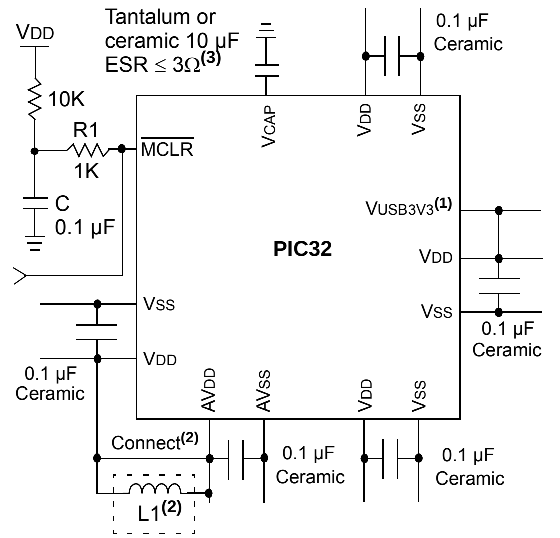
Legend: CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; TTL = TTL input buffer; Analog = Analog input; O = Output; PPS = Peripheral Pin Select; P = Power; I = Input; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to V_{DD}.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between V_{DD} and AV_{DD} to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2} \quad \text{(i.e., ADC conversion rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the V_{CAP} pin, which is used to stabilize the internal voltage regulator output. The V_{CAP} pin must not be connected to V_{DD}, and must have a C_{EFC} capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **30.0 "Electrical Characteristics"** for additional information on C_{EFC} specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

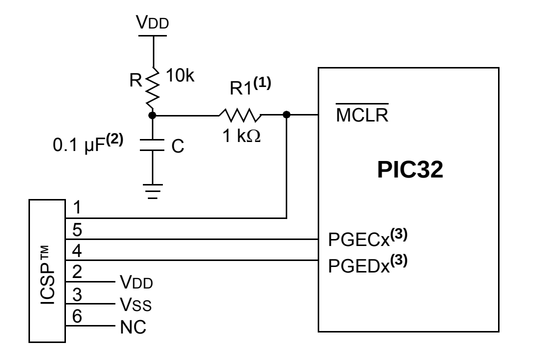
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin V_{IH} and V_{IL} specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Coprocessor 0 also contains the logic for identifying and managing exceptions. Exceptions can be caused by a variety of sources, including alignment errors in data, external events or program errors. Table 3-3 lists the exception types in order of priority.

TABLE 3-3: MIPS32® M4K® PROCESSOR CORE EXCEPTION TYPES

Exception	Description
Reset	Assertion $\overline{MCLR}$ or a Power-on Reset (POR).
DSS	EJTAG debug single step.
DINT	EJTAG debug interrupt. Caused by the assertion of the external *EJ_DINT* input or by setting the EjtagBrk bit in the ECR register.
NMI	Assertion of NMI signal.
Interrupt	Assertion of unmasked hardware or software interrupt signal.
DIB	EJTAG debug hardware instruction break matched.
AdEL	Fetch address alignment error. Fetch reference to protected address.
IBE	Instruction fetch bus error.
DBp	EJTAG breakpoint (execution of `SDBBP` instruction).
Sys	Execution of `SYSCALL` instruction.
Bp	Execution of `BREAK` instruction.
RI	Execution of a reserved instruction.
CpU	Execution of a coprocessor instruction for a coprocessor that is not enabled.
CEU	Execution of a `CorExtend` instruction when `CorExtend` is not enabled.
Ov	Execution of an arithmetic instruction that overflowed.
Tr	Execution of a trap (when trap condition is true).
DDBL/DDBS	EJTAG Data Address Break (address only) or EJTAG data value break on store (address + value).
AdEL	Load address alignment error. Load reference to protected address.
AdES	Store address alignment error. Store to protected address.
DBE	Load or store bus error.
DDBL	EJTAG data hardware breakpoint matched in load data compare.

3.3 Power Management

The MIPS M4K processor core offers many power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or Halting the clocks, which reduces system power consumption during Idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

The mechanism for invoking Power-Down mode is through execution of the `WAIT` instruction. For more information on power management, see **Section 26.0 “Power-Saving Features”**.

3.4 EJTAG Debug Support

The MIPS M4K processor core provides an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard User mode and Kernel modes of operation, the M4K core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a Debug Exception Return (`DERET`) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define which registers are selected and how they are used.

6.1 Reset Control Registers

TABLE 6-1: RESET CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F600	RCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CMR	VREGS	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR	POR	xxxx(2)
F610	RSWRST	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SWRST	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

TABLE 7-1: INTERRUPT IRQ, VECTOR AND BIT LOCATION (CONTINUED)

Interrupt Source[(1)]	IRQ #	Vector #	Interrupt Bit Location				Persistent Interrupt
			Flag	Enable	Priority	Sub-priority	
U1E – UART1 Fault	39	32	IFS1<7>	IEC1<7>	IPC8<4:2>	IPC8<1:0>	Yes
U1RX – UART1 Receive Done	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>	Yes
U1TX – UART1 Transfer Done	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>	Yes
I2C1B – I2C1 Bus Collision Event	42	33	IFS1<10>	IEC1<10>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1S – I2C1 Slave Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1M – I2C1 Master Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>	Yes
CNA – PORTA Input Change Interrupt	45	34	IFS1<13>	IEC1<13>	IPC8<20:18>	IPC8<17:16>	Yes
CNB – PORTB Input Change Interrupt	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>	Yes
CNC – PORTC Input Change Interrupt	47	34	IFS1<15>	IEC1<15>	IPC8<20:18>	IPC8<17:16>	Yes
PMP – Parallel Master Port	48	35	IFS1<16>	IEC1<16>	IPC8<28:26>	IPC8<25:24>	Yes
PMPE – Parallel Master Port Error	49	35	IFS1<17>	IEC1<17>	IPC8<28:26>	IPC8<25:24>	Yes
SPI2E – SPI2 Fault	50	36	IFS1<18>	IEC1<18>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2RX – SPI2 Receive Done	51	36	IFS1<19>	IEC1<19>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2TX – SPI2 Transfer Done	52	36	IFS1<20>	IEC1<20>	IPC9<4:2>	IPC9<1:0>	Yes
U2E – UART2 Error	53	37	IFS1<21>	IEC1<21>	IPC9<12:10>	IPC9<9:8>	Yes
U2RX – UART2 Receiver	54	37	IFS1<22>	IEC1<22>	IPC9<12:10>	IPC9<9:8>	Yes
U2TX – UART2 Transmitter	55	37	IFS1<23>	IEC1<23>	IPC9<12:10>	IPC9<9:8>	Yes
I2C2B – I2C2 Bus Collision Event	56	38	IFS1<24>	IEC1<24>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2S – I2C2 Slave Event	57	38	IFS1<25>	IEC1<25>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2M – I2C2 Master Event	58	38	IFS1<26>	IEC1<26>	IPC9<20:18>	IPC9<17:16>	Yes
CTMU – CTMU Event	59	39	IFS1<27>	IEC1<27>	IPC9<28:26>	IPC9<25:24>	Yes
DMA0 – DMA Channel 0	60	40	IFS1<28>	IEC1<28>	IPC10<4:2>	IPC10<1:0>	No
DMA1 – DMA Channel 1	61	41	IFS1<29>	IEC1<29>	IPC10<12:10>	IPC10<9:8>	No
DMA2 – DMA Channel 2	62	42	IFS1<30>	IEC1<30>	IPC10<20:18>	IPC10<17:16>	No
DMA3 – DMA Channel 3	63	43	IFS1<31>	IEC1<31>	IPC10<28:26>	IPC10<25:24>	No
Lowest Natural Order Priority							

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX1XX 28/36/44-Pin General Purpose Family Features"** and **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"** for the lists of available peripherals.

8.1 Oscillator Control Regiters

TABLE 8-1: OSCILLATOR CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F000	OSCCON	31:16	—	—	PLLODIV<2:0>			FRCDIV<2:0>			—	SOSCRDY	PBDIVRDY	PBDIV<1:0>		PLLMULT<2:0>			x1xx(2)
		15:0	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	ULOCK(3)	SLOCK	SLPEN	CF	UFRCEN(3)	SOSCEN	OSWEN	xxxx(2)
F010	OSCTUN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000
F020	REFOCON	31:16	—	RODIV<14:0>															0000
		15:0	ON	—	SIDL	OE	RSLP	—	DIVSWEN	ACTIVE	—	—	—	—	ROSEL<3:0>				0000
F030	REFOTRIM	31:16	ROTRIM<8:0>									—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

3: This bit is only available on PIC32MX2XX devices.

11.1 Parallel I/O (PIO) Ports

All port pins have 10 registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx, and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than V_{DD} (e.g., 5V) on any desired 5V-tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

11.1.2 CONFIGURING ANALOG AND DIGITAL PORT PINS

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs must have their corresponding ANSEL and TRIS bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

If the TRIS bit is cleared (output) while the ANSELx bit is set, the digital output level (V_{OH} or V_{OL}) is converted by an analog peripheral, such as the ADC module or Comparator module.

When the PORT register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.1.3 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a `NOP`.

11.1.4 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports allows the PIC32MX1XX/2XX 28/36/44-pin Family devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a change-of-state.

Five control registers are associated with the CN functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

The CNSTATx register indicates whether a change occurred on the corresponding pin since the last read of the PORTx bit.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push-button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on change notification pins should always be disabled when the port pin is configured as a digital output.

An additional control register (CNCONx) is shown in Register 11-3.

11.2 CLR, SET and INV Registers

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

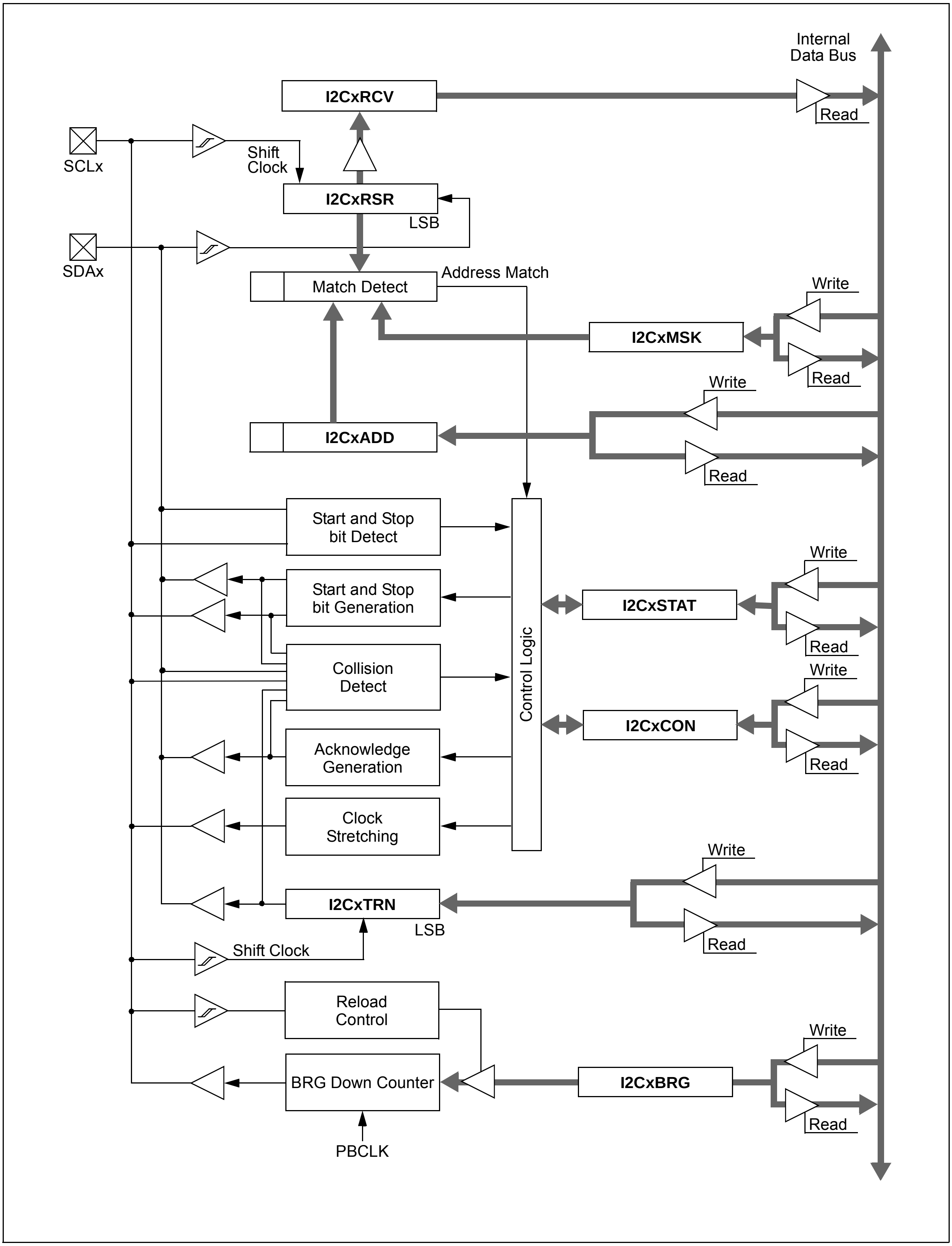
Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR, or INV register, the base register must be read.

TABLE 11-6: PERIPHERAL PIN SELECT INPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FA54	U1CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U1CTSR<3:0>				0000
FA58	U2RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U2RXR<3:0>				0000
FA5C	U2CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U2CTSR<3:0>				0000
FA84	SDI1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI1R<3:0>				0000
FA88	SS1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS1R<3:0>				0000
FA90	SDI2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI2R<3:0>				0000
FA94	SS2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS2R<3:0>				0000
FAB8	REFCLKIR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	REFCLKIR<3:0>				0000

NOTES:

FIGURE 18-1: I²C BLOCK DIAGRAM



REGISTER 19-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 5 **ABAUD:** Auto-Baud Enable bit
1 = Enable baud rate measurement on the next character – requires reception of Sync character (0x55); cleared by hardware upon completion
0 = Baud rate measurement disabled or completed

bit 4 **RXINV:** Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
1 = High-Speed mode – 4x baud clock enabled
0 = Standard Speed mode – 16x baud clock enabled

bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Selection bit
1 = 2 Stop bits
0 = 1 Stop bit

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 21-4: RTCDATE: RTC DATE VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	YEAR10<3:0>				YEAR01<3:0>			
23:16	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	—	MONTH10	MONTH01<3:0>			
15:8	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	DAY10<1:0>		DAY01<3:0>			
7:0	U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
	—	—	—	—	—	WDAY01<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-28 **YEAR10<3:0>:** Binary-Coded Decimal Value of Years bits, 10s place digit; contains a value from 0 to 9

bit 27-24 **YEAR01<3:0>:** Binary-Coded Decimal Value of Years bits, 1s place digit; contains a value from 0 to 9

bit 23-21 **Unimplemented:** Read as ‘0’

bit 20 **MONTH10:** Binary-Coded Decimal Value of Months bits, 10s place digit; contains a value of 0 or 1

bit 19-16 **MONTH01<3:0>:** Binary-Coded Decimal Value of Months bits, 1s place digit; contains a value from 0 to 9

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-12 **DAY10<1:0>:** Binary-Coded Decimal Value of Days bits, 10s place digit; contains a value of 0 to 3

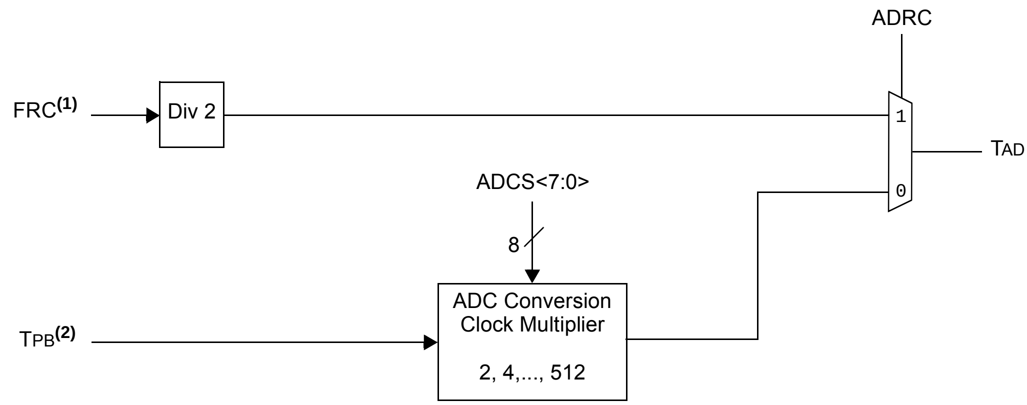
bit 11-8 **DAY01<3:0>:** Binary-Coded Decimal Value of Days bits, 1s place digit; contains a value from 0 to 9

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2-0 **WDAY01<2:0>:** Binary-Coded Decimal Value of Weekdays bits; contains a value from 0 to 6

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: See **Section 30.0 "Electrical Characteristics"** for the exact FRC clock value.

2: Refer to Figure 8-1 in **Section 8.0 "Oscillator Configuration"** for more information.

25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note:	This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 37. "Charge Time Measurement Unit (CTMU)"** (DS60001167), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

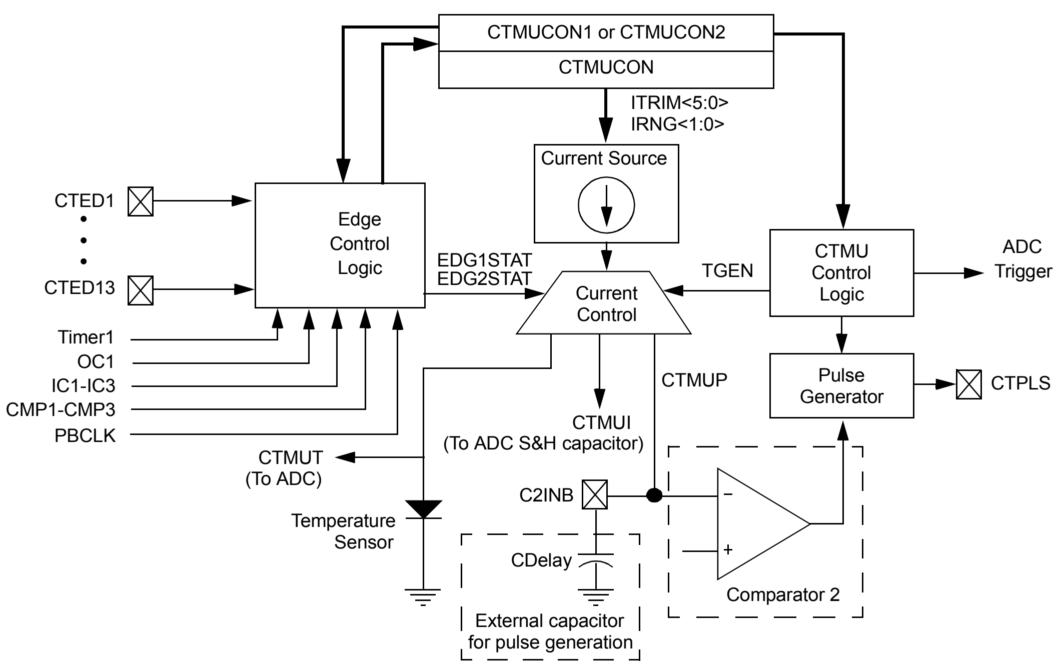
The Charge Time Measurement Unit (CTMU) is a flexible analog module that has a configurable current source with a digital configuration circuit built around it. The CTMU can be used for differential time measurement between pulse sources and can be used for generating an asynchronous pulse. By working with other on-chip analog modules, the CTMU can be used for high resolution time measurement, measure capacitance, measure relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

The CTMU module includes the following key features:

- Up to 13 channels available for capacitive or time measurement input
- On-chip precision current source
- 16-edge input trigger sources
- Selection of edge or level-sensitive inputs
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- High precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Integrated temperature sensing diode
- Control of current source during auto-sampling
- Four current source ranges
- Time measurement resolution of one nanosecond

A block diagram of the CTMU is shown in Figure 25-1.

FIGURE 25-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMUT	0	EDG1STAT = EDG2STAT
CTMUI	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
No Connect	1	EDG1STAT = EDG2STAT

REGISTER 27-3: DEVCFG2: DEVICE CONFIGURATION WORD 2 (CONTINUED)

bit 2-0 **FPLLIDIV<2:0>:** PLL Input Divider bits

`111` = 12x divider
`110` = 10x divider
`101` = 6x divider
`100` = 5x divider
`011` = 4x divider
`010` = 3x divider
`001` = 2x divider
`000` = 1x divider

Note 1: This bit is only available on PIC32MX2XX devices.

TABLE 30-5: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-temp		
Parameter No.	**Typical(3)**	**Max.**	**Units**	**Conditions**	
Operating Current (I_{DD}) (Notes 1, 2, 5)					
DC20	2	3	mA	4 MHz **(Note 4)**	
DC21	7	10.5	mA	10 MHz	
DC22	10	15	mA	20 MHz **(Note 4)**	
DC23	15	23	mA	30 MHz **(Note 4)**	
DC24	20	30	mA	40 MHz	
DC25	100	150	µA	+25ºC, 3.3V	LPRC (31 kHz) **(Note 4)**

Note 1: A device's I_{DD} supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for I_{DD} measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}
- CPU executing `while(1)` statement from Flash
- RTCC and JTAG are disabled

3: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

4: This parameter is characterized, but not tested in manufacturing.

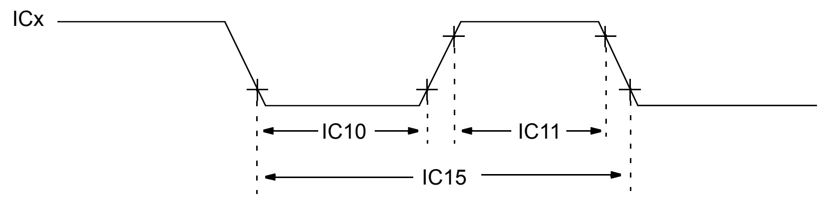
5: I_{PD} electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

TABLE 30-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**		**Min.**	**Max.**	**Units**	**Conditions**	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of [(25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of [(25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-7: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-25: INPUT CAPTURE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TCCL	ICx Input Low Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	N = prescale value (1, 4, 16)
IC11	TCCH	ICx Input High Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	
IC15	TCCP	ICx Input Period	[(25 ns or 2 TPB)/N] + 50 ns	—	ns	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics(1)	Min.	Typical(2)	Max.	Units	Conditions
SP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance **(Note 4)**	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	SSx ↑ after SCKx Edge	Tsck + 20	—	—	ns	—
SP60	TssL2doV	SDOx Data Output Valid after SSx Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

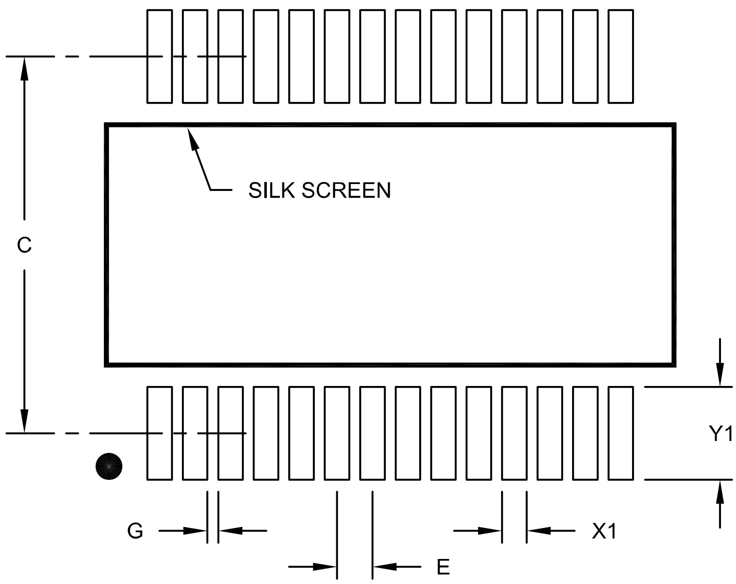
2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A